

A B S T R A C T

Provided are a sheet and a thermally curable composition that are capable of reducing gas trapped between an electronic component and a thermally curable composition, and that can suppress occurrence of flow marks. A method for manufacturing a device is provided for which the amount of internal voids, unevenness, pinholes, and flow marks is small.

This relates to a sheet-like thermally curable composition comprising a phenolic resin, an inorganic filler, and silicone-type particles. This relates to a sheet comprising a thermally curable composition. This relates to a device manufacturing method comprising an operation in which a thermally curable composition is arranged over an electronic component, an operation in which a composite body is formed, and an operation in which heating of the composite body causes curing of the thermally curable composition to occur.